

RoHS

COMPLIANT

P-Channel 30-V (D-S) MOSFET

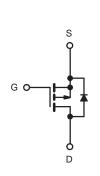
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)		
- 30	0.011 at V _{GS} = - 10 V	- 13.5	29.5 nC		
	0.015 at V_{GS} = - 4.5 V	- 11.6	29.0 110		

FEATURES

- Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

APPLICATIONS

- Load Switch
- Notebook Adaptor Switch



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_A	= 25 °C, unless othe	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 30	V	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		- 13.5		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C		- 11.9		
Continuous Drain Current (1) = 150°C)	T _A = 25 °C	I _D	- 10.9 ^{a, b}		
	T _A = 70 °C		- 8.6 ^{a, b}	A	
Pulsed Drain Current	I _{DM}	- 50	A		
Ocationa Daria Dista Ocament	T _C = 25 °C	1	- 4.1		
Continuous Source-Drain Diode Current	T _A = 25 °C	Is –	- 2.2 ^{a, b}		
Avalanche Current		I _{AS}	- 20		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ	
	T _C = 25 °C		5.0		
Maximum Dawar Dissinction	T _C = 70 °C		3.2	w	
Maximum Power Dissipation	T _A = 25 °C	P _D —	2.7 ^{a, b}	vv	
	T _A = 70 °C]	1.7 ^{a, b}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

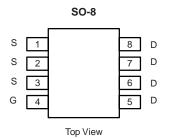
THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	C/W	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 85 °C/W. d. Based on $T_C = 25$ °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static					-	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 µA	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$			- 34		mV/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.3		°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1.4		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			± 100	nA
5		$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 30			A
		$V_{GS} = -10 \text{ V}, I_D = -10 \text{ A}$		0.011		ł
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 8 A		0.015		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S
Dynamic ^b		1				
Input Capacitance	C _{iss}			2550		
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		455		pF
Reverse Transfer Capacitance	C _{rss}			390		1
Total Gate Charge		V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 10 A		57	86	nC
	Q _g			29.5	45	
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 10 A		8		
Gate-Drain Charge	Q _{qd}			22		1
Gate Resistance	R _q	f = 1 MHz	0.5	2.2	4.4	Ω
Turn-On Delay Time	t _{d(on)}			13	25	
Rise Time	t _r	V_{DD} = - 15 V, R _L = 1.5 Ω		12	24	1
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_q = 1 Ω		40	70	1
Fall Time	t _f			9	18	1
Turn-On Delay Time	t _{d(on)}			48	80	ns
Rise Time	t _r	V_{DD} = - 15 V, R _L = 1.5 Ω		92	160	1
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 4.5 V, R_q = 1 Ω		34	60	1
Fall Time	t _f			19	35	1
Drain-Source Body Diode Characteris	stics					
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	^
Pulse Diode Forward Current	I _{SM}				- 60	A
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			27	45	ns
Body Diode Reverse Recovery Charge Q _{rr}				16	27	nC
Reverse Recovery Fall Time	ta	I _F = - 10 A, dI/dt = 100 A/μs, T _J = 25 °C		12		
Reverse Recovery Rise Time	t _b			15		ns

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

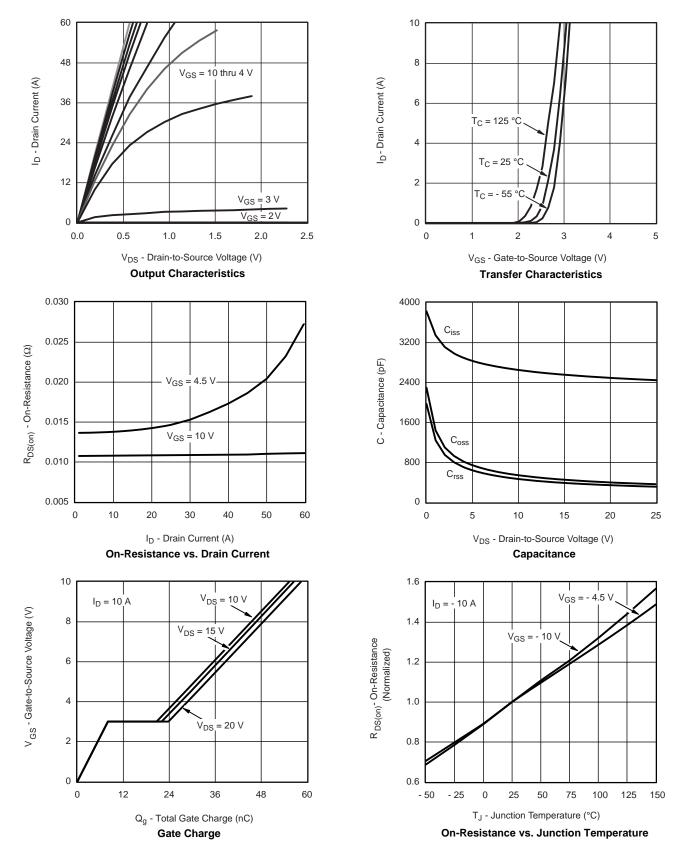
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

emi









I_D = 10 A

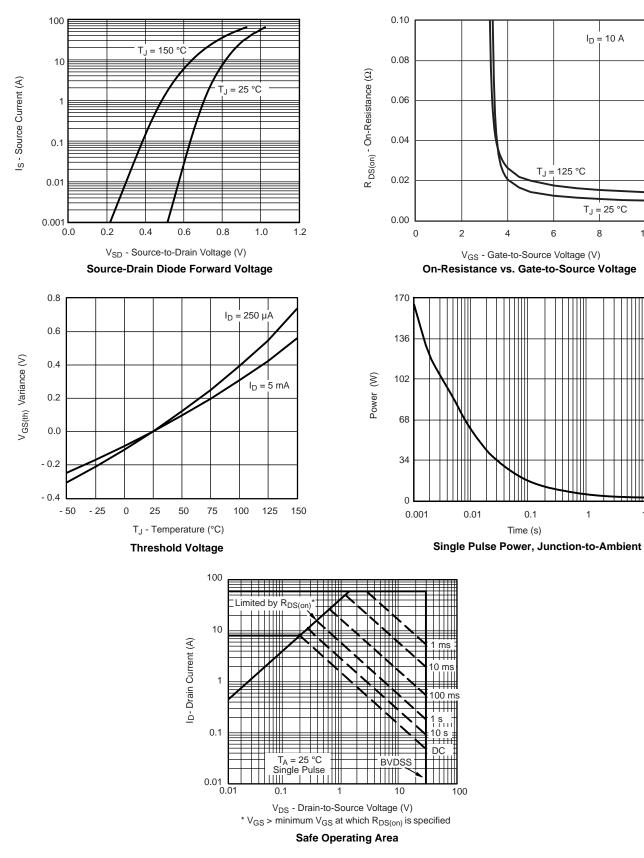
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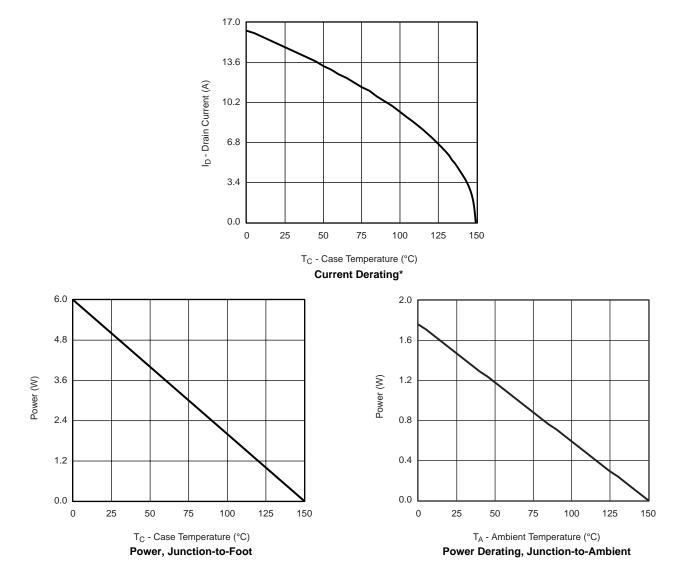
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





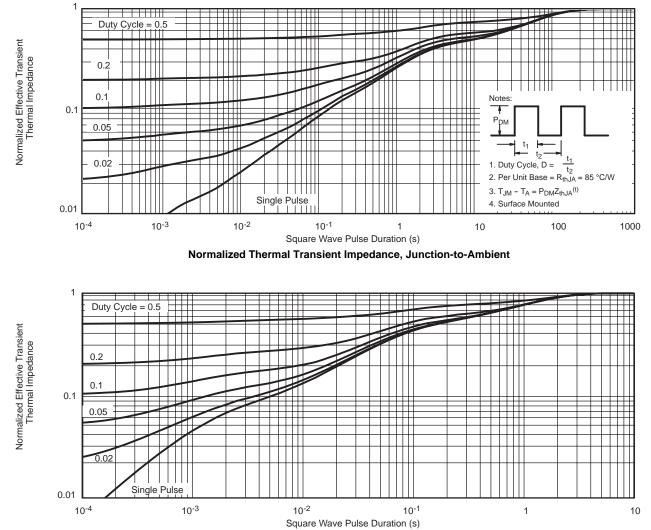
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

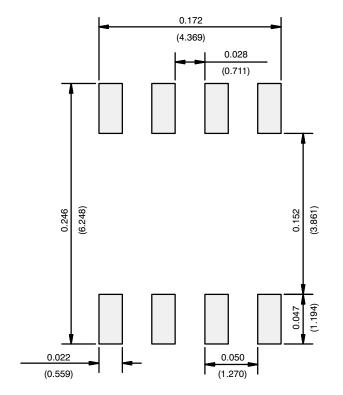




	MILLIMETERS		INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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